

PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION

Part Number: [0737690100](#)
Status: **Active**
Overview: [hdm](#)
Description: 2.00mm (.079") Pitch HDM® Board-to-Board Stacking Header, High Rise Vertical, Press-Fit, Open End Option, 72 Circuits

Documents:

[3D Model](#) [Product Specification PS-73780-999 \(PDF\)](#)
[Drawing \(PDF\)](#) [RoHS Certificate of Compliance \(PDF\)](#)

Agency Certification

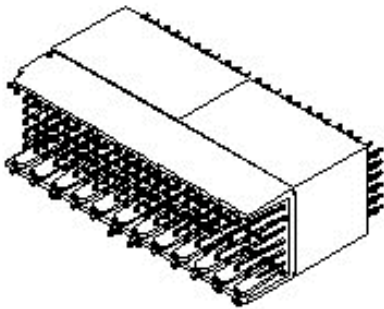
CSA LR19980
UL E29179

General

Product Family Backplane Connectors
Series [73769](#)
Application Backplane, Mezzanine
Component Type PCB Header
Overview [hdm](#)
Product Name HDM®
Style N/A

Physical

Circuits (Loaded) 72
Circuits (maximum) 72
Color - Resin Black
Durability (mating cycles max) 200
First Mate / Last Break No
Flammability 94V-0
Guide to Mating Part No
Keying to Mating Part None
Material - Metal Phosphor Bronze
Material - Plating Mating Gold
Material - Plating Termination Tin-Lead
Material - Resin High Temperature Thermoplastic
Number of Columns 12
Number of Pairs Open Pin Field
Number of Rows 6
Orientation Vertical
PC Tail Length (in) 0.138 In
PC Tail Length (mm) 3.50 mm
PCB Retention None
PCB Thickness Recommended (in) 0.055 In
PCB Thickness Recommended (mm) 1.40 mm
Packaging Type Tube
Pitch - Mating Interface (in) 0.079 In
Pitch - Mating Interface (mm) 2.00 mm
Plating min: Mating (µin) 30
Plating min: Mating (µm) 0.75
Plating min: Termination (µin) 15
Plating min: Termination (µm) 0.375
Polarized to PCB No
Stackable Yes
Surface Mount Compatible (SMC) Yes
Temperature Range - Operating -55°C to +105°C



Series

image - Reference only

EU RoHS

RoHS Compliant by Exemption

REACH SVHC

Contains SVHC: No

Halogen-Free

Status

Halogen-Free

China RoHS



Need more information on product environmental compliance?

Email productcompliance@molex.com
For a multiple part number RoHS Certificate of Compliance, [click here](#)

Please visit the [Contact Us](#) section for any non-product compliance questions.

Search Parts in this Series

[73769Series](#)

Mates With

[73632](#) HDM PLUS® Board-to-Board Daughtercard Receptacle. [73780](#) HDM® Board-to-Board Daughtercard Receptacle

Application Tooling | FAQ

Tooling specifications and manuals are found by selecting the products below. Crimp Height Specifications are then contained in the Application Tooling Specification document.

Global

Description	Product #
Flat Rock Tooling for	0622013700
Pneumatic Press	

Termination Interface: Style

Through Hole - Compliant Pin

Electrical

Current - Maximum per Contact

1A

Data Rate

1.0 Gbps

Real Signals (per 25mm)

72

Voltage - Maximum

100V AC

Material Info

Reference - Drawing Numbers

Packaging Specification

PK-70873-0870

Product Specification

PS-73780-999

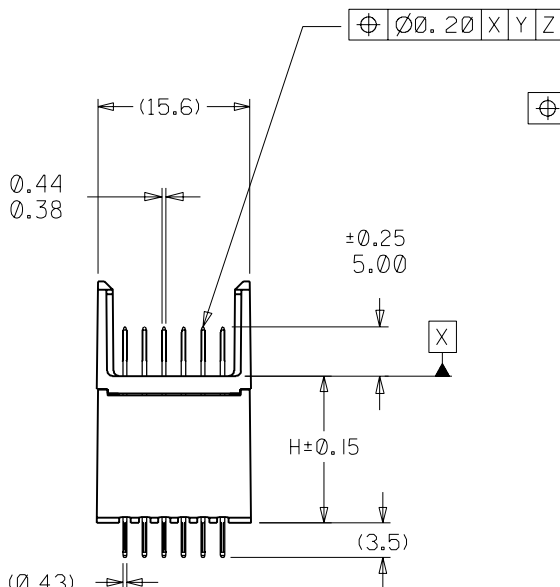
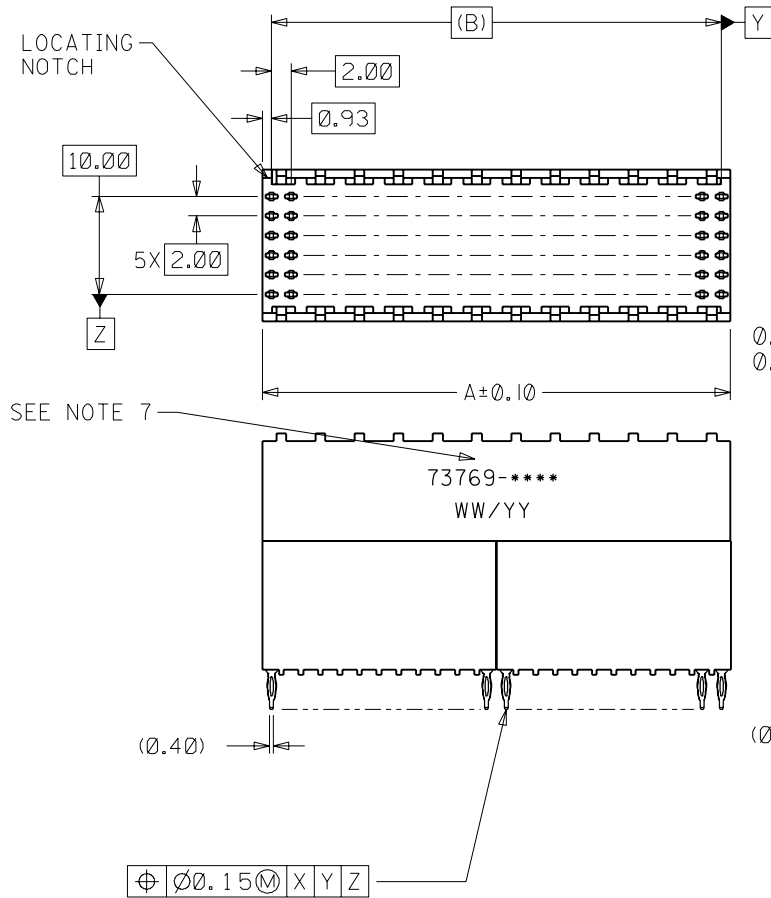
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This document was generated on 05/25/2010

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- NOTES:
1. MATERIALS: HOUSING-LIQUID CRYSTAL POLYMER (LCP), GLASS-FILLED, UL94V-0, COLOR: BLACK. TERMINAL-PHOSPHOR BRONZE
 2. FINISH: SELECTIVE GOLD (Au) IN CONTACT AREA, 0.00076mm MINIMUM THICKNESS; SELECTIVE TIN/LEAD (Sn/Pb) ON TAILS, NICKEL (Ni) OVERALL.
 3. THIS PART CONFORMS TO MOLEX PRODUCT SPECIFICATION PS-73780-999.
 4. DIMENSIONS ARE IN MILLIMETERS.
 5. RECOMMENDED PCB THICKNESS: 2.50 MINIMUM.
 6. PACKAGE PER PK-70873-0870, PK-70873-0871, OR PK-70873-0875.
 7. PARTS MARKED WITH PART NUMBER AND DATE CODE APPROXIMATELY WHERE SHOWN.

ASSEMBLY P/N	TOTAL NUMBER OF SIGNAL CONTACTS	DIM "A"	DIM "B"	DIM "H"
73769-0100	72	23.84	22.00	15.05
73769-0200	72	23.84	22.00	6.05
73769-0300	72	23.84	22.00	10.05
73769-1100	144	47.84	46.00	15.05
73769-1200	144	47.84	46.00	6.05
73769-1300	144	47.84	46.00	10.05



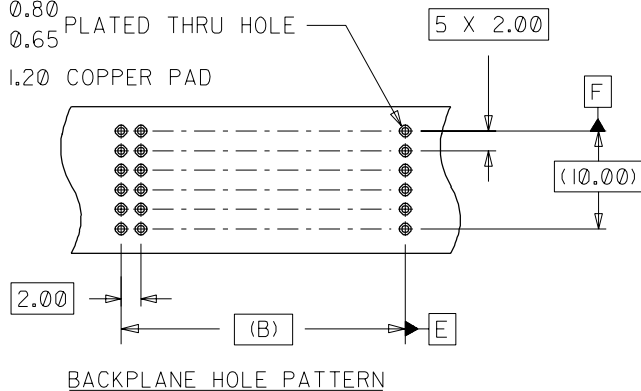
⌀ 0.15 (M) E F

⌀ 0.838 DRILL

⌀ 0.80 PLATED THRU HOLE

⌀ 0.65

⌀ 1.20 COPPER PAD



REVISED

EC NO. UDT2000-1073

DRWN: BINGHAM 00/05/08

CHK: REED 00/05/08

APPR: BIXLER 00/05/08

F

DESCRIPTION

MAJOR

CRITICAL

REV

GENERAL TOLERANCES: (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± 0.	± .
3 PLACES	± 0.	± .
2 PLACES	± 0.05	± .
1 PLACE	± 0.10	± .

ANGULAR: ± 1/2°

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

SCALE 2:1

DESIGN UNITS

THIRD ANGLE PROJECTION

TITLE: SALES ASSEMBLY

HDM BACKPLANE STACKING MODULE

OPEN END OPTION PRESSFIT

MOLEX INCORPORATED

MATERIAL NO. SEE CHART

DRAWING NO. SD-73769-001

SHEET NO. 1 OF 1

SIZE B

Данный компонент на территории Российской Федерации

Вы можете приобрести в компании MosChip.

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

<http://moschip.ru/get-element>

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

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